Model 4800
Die Ejector Grid System

Best way to Manually Remove Die from Wafer Dicing Tape

A specially designed vacuum system that draws tape away from the die while supporting the die on the grid.

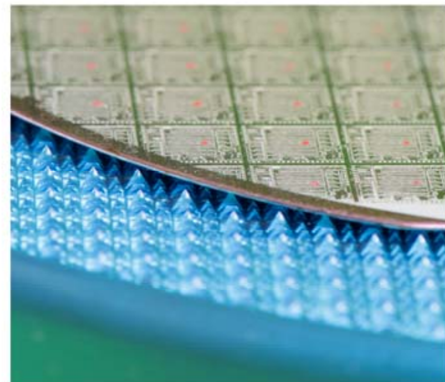
Die maintain position until easily picked up with a hand held vacuum tool.

Particularly good for use on thin die and laser bars.

Works with UV curable and pressure sensitive tapes.

Can be mounted on SEC Pick & Place System Model 835

SEC stocks UV and pressure sensitive Dicing and Backgrinding Tape.



Specifications:

- Power: 115V, 3 amps, 50/;60 Hz or
- Power: 220V, 1 amp, 50Hz
- Vacuum: 25inHg
- Weight: 6 lbs
- Shipping Weight: 9 lbs
- Size: 8” wide X 5” high x 5” deep

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